

CLAIMS

What is claimed is:

5 1. A package of a semiconductor device with a flexible wiring substrate,
comprising:

a semiconductor substrate with at least one pad on a surface thereof;

a bump bonded to said pad;

an adhesive layer on said bump; and

10 a flexible wiring substrate having at least one contact section being
electrically connected with said bump by said adhesive layer.

2. The package of claim 1, wherein said bump is stud bump.

15 3. The package of claim 2, wherein said bump is gold stud bump.

4. The package of claim 1, wherein said adhesive layer includes non-
conductive paste.

20 5. The package of claim 2, wherein said adhesive layer includes non-
conductive paste.

6. The package of claim 1, wherein said adhesive layer includes anisotropic
conductive paste.

25 7. The package of claim 2, wherein said adhesive layer includes anisotropic

conductive paste.

8. The package of claim 1, wherein said semiconductor substrate having image sensors on the surface thereof having said pad.

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9. The package of claim 8, wherein a transparent plate covered on the surface of said semiconductor substrate having said image sensors.

10. The package of claim 9, wherein said bump is stud bump.

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11. The package of claim 10, wherein said adhesive layer includes anisotropic conductive paste.

12. The package of claim 10, wherein said adhesive layer includes non-
15 conductive paste.

13. A package method of a semiconductor device with a flexible wiring substrate, comprising:

20 providing a semiconductor substrate having at least one pad on a surface thereof;

forming a bump on said pad of said semiconductor substrate;

forming an adhesive layer on said bump; and

attaching a flexible wiring substrate unto said semiconductor substrate, wherein said flexible wiring substrate is provided with at least one contact
25 section, and said contact section is electrically connected with said pad by said adhesive layer.

14. The package method of claim 13, wherein said bump is formed by a stud bump process.

5 15. The package method of claim 14, wherein said bump is formed by a gold stud bump process.

16. The package method of claim 13, wherein said adhesive layer includes non-conductive paste.

10 17. The package method of claim 14, wherein said adhesive layer includes non-conductive paste.

15 18. The package method of claim 13, wherein said adhesive layer includes anisotropic conductive paste.

19. The package method of claim 14, wherein said adhesive layer includes anisotropic conductive paste.

20 20. The package method of claim 16, wherein said adhesive layer includes epoxy-based non-conductive paste.